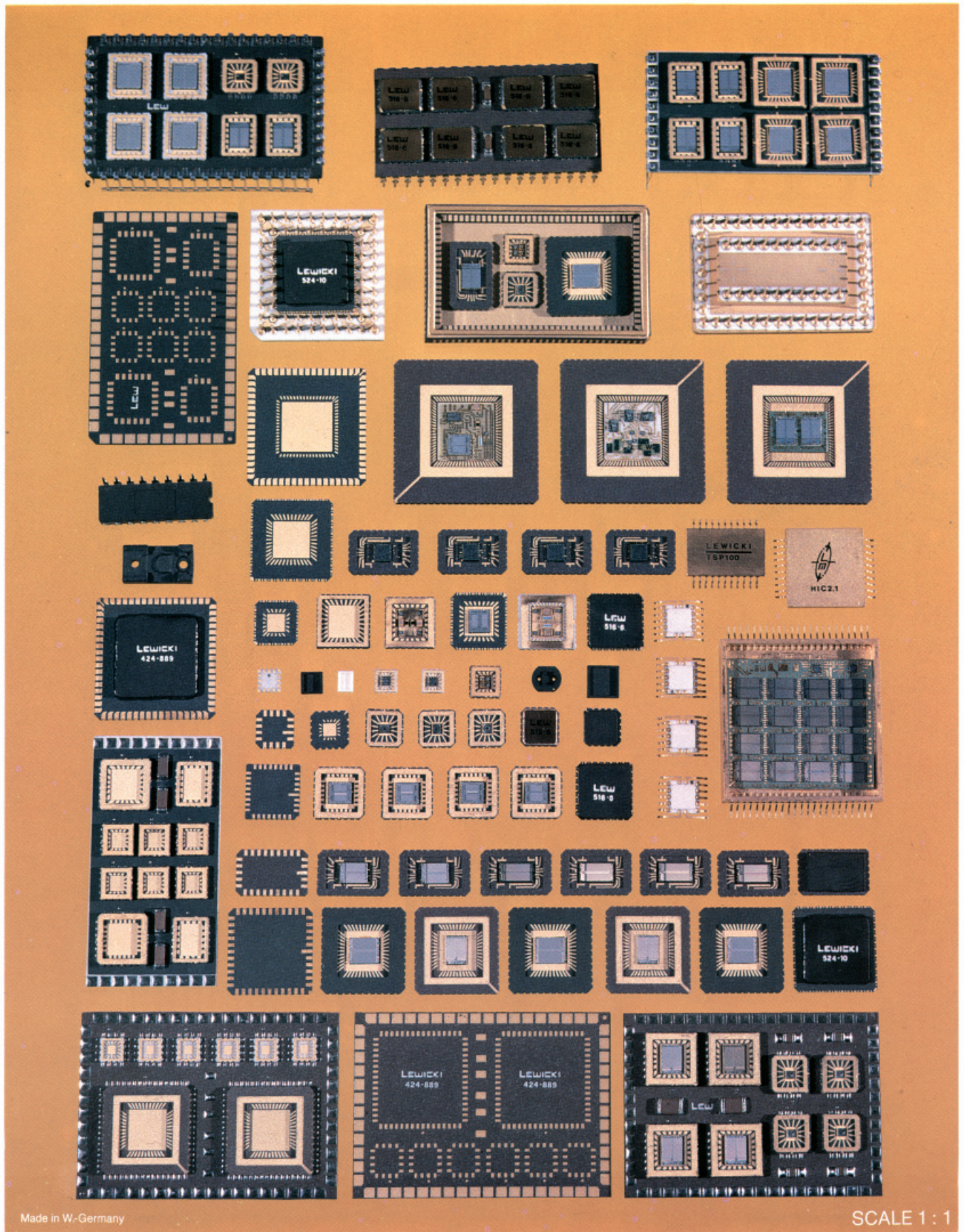


Chip Carrier Packaging

für industrielle/kommerzielle/professionelle Applikationen + MIL



Made in W-Germany

SCALE 1 : 1

- ★ all Carriers and Flatpacks
- ★ pin grid/ plug-in/ DIL
- ★ single and multilayer
- ★ JEDEC 40 and 50 mil lead spacing (1.0 and 1.27 mm)
- ★ lead counts up to 300+

- ★ UV glass window lids
- ★ beryllia power packs
- ★ black and white ceramic (+ low alpha for MOS)
- ★ metal and plastic base
- ★ hermetic sealing by welding/brazing/glass

- ★ protective inert atmosp. (with positive pressure)
- ★ nonhermetic epoxy seal
- ★ all types of chips
- ★ VLSI, LSI, MSI, ICS,

- ★ gate array chips
- ★ transistors, diodes,
- ★ opto, CCD, RC networks
- ★ gold or aluminium wire
- ★ eutectic or epoxy die attach etc.

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